



OL-IP4369CX4

wafer level chip-size package; 4 bumps (2 x 2); 0.4 mm pitch;
0.76 mm x 0.76 mm x 0.47 mm body

8 June 2017

Package information

1. Package summary

Terminal position code	B (bottom)
Package type descriptive code	WLCSP
Package type industry code	WLCSP
Package style descriptive code	UC (uncased chip)
Package body material type	X (other)
Mounting method type	S (surface mount)
Issue date	25-5-2007
Manufacturer package code	WLCSP4

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	0.71	-	0.76	0.81	mm
E	package width	0.71	-	0.76	0.81	mm
A	seated height	0.44	-	0.47	0.5	mm
A ₂	package height	0.26	-	0.27	0.28	mm
e	nominal pitch	-	-	0.4	-	mm
n ₂	actual quantity of termination	-	-	4	-	

2. Package outline

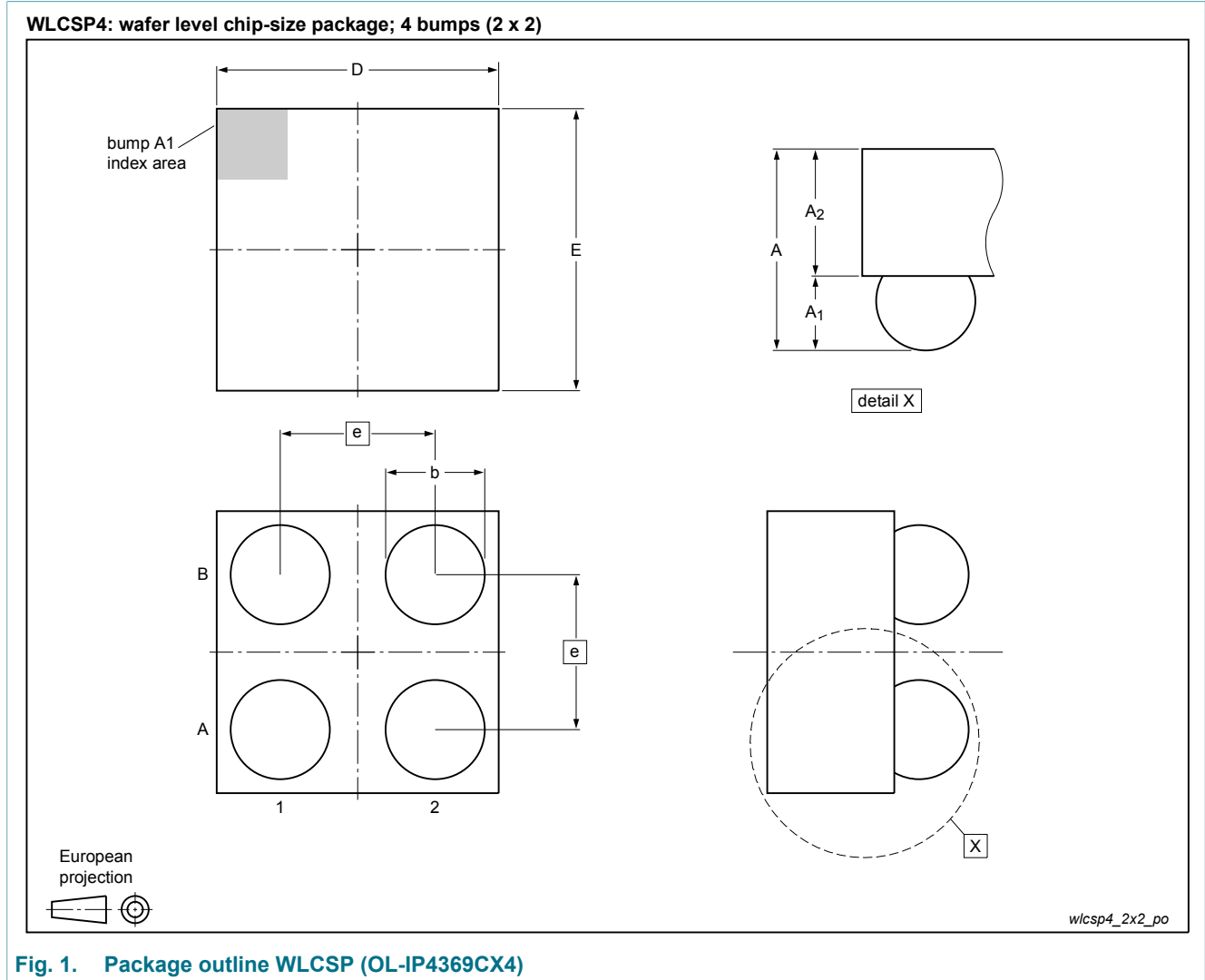


Fig. 1. Package outline WLCSP (OL-IP4369CX4)

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3. Legal information

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